



Material Content Data Sheet



Sales Product Name		BTN8982TA		Issued		4. July 2019		
MA#		MA003664518						
Package		PG-TO263-7-1		Weight*		1533.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.086	0.27	0.27	2665	2665
chip_2	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	791	791
chip_3	inorganic material	silicon	7440-21-3	1.916	0.12	0.12	1250	1250
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
	non noble metal	copper	7440-50-8	808.613	52.76	52.83	527462	528148
wire	non noble metal	aluminium	7429-90-5	11.724	0.76	0.76	7648	7648
encapsulation	organic material	carbon black	1333-86-4	8.717	0.57		5686	
	plastics	epoxy resin	-	95.887	6.25		62548	
	inorganic material	silicondioxide	60676-86-0	476.531	31.08	37.90	310844	379078
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8504	8504
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	139	140
solder	non noble metal	tin	7440-31-5	0.066	0.00		43	
	noble metal	silver	7440-22-4	0.082	0.01		54	
	non noble metal	lead	7439-92-1	3.141	0.20	0.21	2049	2146
glue	plastics	Polyimide	26023-21-2	0.396	0.03	0.03	259	259
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69281	69371
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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